MOMENTIVE

Silicone Materials for Electronic Devices and Component Assemblies



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Silicone Product Profile

The products introduced in this selector guide consist of RTV (Room Temperature Vulcanizing) silicone products that are commonly found in Electric and Electronic applications and component assemblies. This family of silicone products consists of both Room Temperature Cure and Heat (Addition) Cure grades.

Momentive Performance
Materials offers a
comprehensive portfolio of
silicone solutions to help meet
a broad array of handling
and performance needs in
electronic components and
assemblies. Selection of
the appropriate type of RTV
depends upon the required
manufacturing process,
handling requirements, curing
conditions, equipment, and
desired material properties.

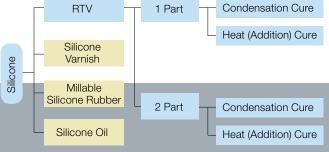
Condensation Cure

Condensation cure silicone products cure when exposed to moisture in the environment at room temperature. These materials are categorized into Alkoxy, Acetoxy, or Oxime based on the byproducts that occur during cure.

Heat (Addition) Cure

Heat cure grades cure upon exposure to elevated heat or room temperature.







Relative Performance Characteristics

Property	Silicone RTV	Ероху	Urethane
Temperature Range	-50 ~ +200 °C	-50 ~ +150 °C	-30 ~ +120 °C
Heat Resistance	Good	Poor	Poor
Flame Retardancy ¹	Good	None	None
UV Stability	Good	Poor	Poor
Ozone Stability	Good	Poor	Poor
Modulus	Low	High	High

¹As a base material silicone demonstrates flame retardant properties comparable to UL94HB.

Sealing & Adhesion

Silicones are used in a wide array of applications for bonding components, and sealing against moisture or environmental contaminants. A comprehensive portfolio of 1 Part and 2 Part Adhesives and Sealants, many of which are excellent candidates for assembly applications on or near sensitive electrical and electronic components, are available. These materials are applied by a variety of methods ranging from manual dispensing to autodispensing units for tube, cartridge, pail, or drum packages. Mixing for 2 Part grades may be accomplished by either manual processes



or meter mix dispensing, depending on production volume and post-mix material properties.

Performance Considerations

- Temperature Resistance
- Dielectric Resistance - Flame Retardancy
- Low Volatility
- Adhesion
- Mechanical Strength
- Hardness
- Thermal Conductivity

Process Considerations

- Viscosity
- Cure Mechanism
- Cure Temperature
- Cure Time
- Pot Life

Coating

The Coating process involves the application of silicone in a thin protective layer to a component surface by methods such as dip, flow, spray, and selective robotic





Performance Considerations

- Temperature Resistance
- Dielectric Resistance
- Flame Retardancy
- Low Volatility

Process Considerations

- Viscosity
- Cure Mechanism
- Cure Temperature
- Cure Time
- Pot Life



Silicone rubber and gels are widely used in electronics to ensure mechanical and environmental protection. A full range of products are offered in various cure speeds, viscosities, and

performance, many of which offer enhancements for thermal cycling protection, stress relief, material strength, flame retardancy, or optical clarity.



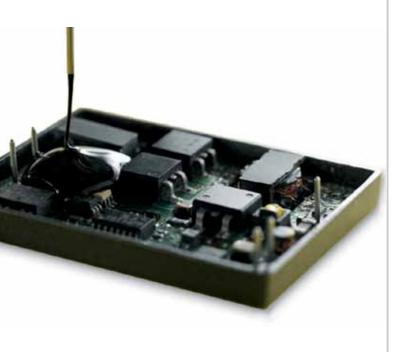
Performance Considerations

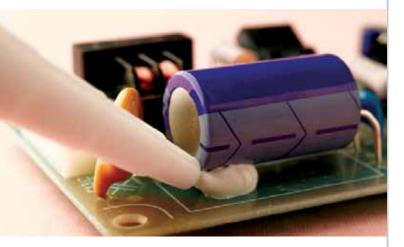
- Temperature Resistance
- Dielectric Resistance
- Flame Retardancy
- Low Volatility
- Adhesion
- Stress Relief
- Release PropertiesThermal Conductivity

Process Considerations

- Viscosity
- Cure Mechanism
- Cure Temperature
- Cure Time
- Pot Life







Industries Served

Electronic Devices and Power Modules

Momentive Performance
Materials is a driving force
as a supplier of advanced
silicone technology to
the electronics industry.
Increasing electronic
component densities and
performance demands have
created a need for specialized
silicone solutions from
Momentive for a broad mix
of performance and handling
requirements.

Typical Applications:

- Power converters
- Inverters
- Hybrid ICs
- Micro-Electronic packaging
- High-voltage component insulation
- Membrane switches
- Photo couplers

Board Assembly

Silicones are found in board-level adhesion, coating, and encapsulation applications, and contribute to the long-term, reliable performance of many components and assemblies. A wide portfolio of products is available, providing flame retardancy, thermal conductivity, temperature resistance, low-volatility, or high-purity benefits.

Typical Applications:

- Board-level adhesion, fixing, and sealing
- PCB coating
- Component encapsulation
- Junction Coating Resins

Consumer Electronics

Silicones are commonly used in a variety of consumer electronics applications. In addition to providing adhesion to many substrates, an array of grades are available to provide heat resistance, flame retardancy, low volatility for sensitive components, and moisture protection.

Typical Applications:

- Flat panel displays
- PCs and Smart Phones
- LED Lighting
- Air conditioner units
- Control panel insulation
- PCB fixing and sealing



Automotive Electronics

The automotive industry plays a critical role in integrating new electronic technologies. As more and more components migrate to electronic solutions, silicones play an increasingly important role in helping deliver material solutions that contribute to design flexibility and long-term component reliability under harsh operating conditions.

Typical Applications:

- ECU potting, sealing, coating
- Wire connector sealing
- Sealing, encapsulation in a broad range of sensors
- HVAC system sealing
- Vibration dampening
- Headlamp assemblies

Aviation and Aerospace

Avionics and frame assembly needs in Aviation and Aerospace are served through silicone adhesives, coating, encapsulation and potting materials that help withstand stress and temperature extremes.

Typical Applications:

- Avionics
- Circuit and terminal protection
- Wire sealants
- Engine gasketing
- Cargo door, window sealing
- Weatherstrip adhesives
- Aviation lighting
- Ventilation ducts



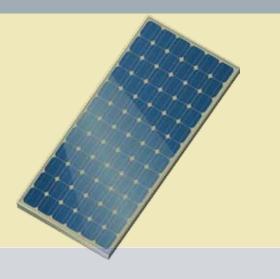


Energy

Reliability of electronic components and the ability for panels to withstand harsh conditions over the lifecycle of the product are important considerations in solar energy applications. Momentive Performance Materials helps serve this growing industry with its range of potting materials and sealants.

Typical Applications:

- Terminal box potting
- Box and base sealing
- Aluminum frame and glass / EVA plate sealing



Product Overview: Adhesives & Sealants

Туре	Grade	Cure Chemistry	Cured Property	Feature
	RTV133	Alkoxy	Rubber	UL certified non-flowable sealant.
	RTV167	Alkoxy	Rubber	High-strength paste adhesive with UL certification and Mil Spec.
	TSE385	Alkoxy	Rubber	Paste adhesive.
	TSE3853-W	Alkoxy	Rubber	UL certified, semi-flowable paste.
	TSE3854DS	Alkoxy	Rubber	UL certified paste adhesive.
	TN3005	Alkoxy	Rubber	Fast tack, low volatile paste paste adhesive.
	TN3085	Alkoxy	Rubber	Fast tack, low volatile paste paste adhesive. UL certified
	TSE3941M	Alkoxy	Rubber	Fast tack, thermally conductive flowable sealant.
	TSE3944	Alkoxy	Rubber	Low volatile, UL certified flowable sealant.
P	TN3305	Alkoxy	Rubber	Fast tack, low volatile flowable adhesive / sealant. UL certified
Ar.	TSE3971	Alkoxy	Rubber	Flowable adhesive / sealant.
\circ	TSE3976-B	Alkoxy	Rubber	Low volatile, temperature resistant sealant. UL certified.
Part Condensation Cure	XE11-B5320	Alkoxy	Rubber	Fast tack, low volatile, thermally conductive adhesive. UL certified.
der	FRV1106	Acetoxy	Rubber	Fuel, solvent, chemical, and temperature-resistant fluoro sealant.
SSC	RTV100 series	Acetoxy	Rubber	FDA, USDA, and NSF compliant paste adhesive. Mil Spec.
atic	RTV106	Acetoxy	Rubber	Temperature-resistant adhesive. FDA, USDA, & NSF compliant. Mil Spec.
S	RTV116	Acetoxy	Rubber	Temperature-resistant flowable sealant. FDA, USDA, & NSF compliant. Mil Spec.
\circ	RTV157	Acetoxy	Rubber	High strength paste / adhesive.
Jre	RTV159	Acetoxy	Rubber	High strength paste / adhesive. Temperature-resistant.
	TSE370	Acetoxy	Rubber	Fast tack, general purpose paste adhesive.
	TSE382	Oxime	Rubber	Fast tack, general purpose adhesive paste. UL certified.
	TSE3826	Oxime	Rubber	Fast tack adhesive for high-temperature applications.
	TSE3843-W	Oxime	Rubber	UL certified general purpose adhesive / sealant.
	TSE384-B	Oxime	Rubber	UL certified general purpose adhesive / sealant.
	TSE387	Oxime	Rubber	General purpose flowable adhesive / sealant.
	TSE3877-B	Oxime	Rubber	Flowable sealant for high-temperature applications.
	TSE388	Oxime	Rubber	Flowable general purpose adhesive / sealant.
	TSE3212	Heat	Rubber	Thixotropic adhesive / sealant.
	TSE322	Heat	Rubber	Flowable adhesive / sealant.
<u> </u>	TSE3221S	Heat	Rubber	Flowable adhesive / sealant.
Part He	TSE322S	Heat	Rubber	UL certified, semi-flowable adhesive / sealant.
-	TSE326	Heat	Rubber	UL certified, high temperature-resistant adhesive / sealant.
- de	TSE3261-G	Heat	Rubber	High temperature-resistant adhesive / sealant.
at o	TSE326M ¹	Heat	Rubber	High temperature-resistant adhesive / sealant.
Cure	TSE3280-G	Heat	Rubber	Thermally conductive adhesive.
6	TSE3281-G	Heat	Rubber	Thermally conductive adhesive.
	XE13-B3208	Heat	Rubber	General purpose adhesive / sealant.
	LA650S	Heat	Rubber	Adhesive that cures to a tough silicone elastomer.
곡 원	RTV577	Condensation	Rubber	Extreme low temperature resistant sealant. Release capability.
Ĥτ	RTV88	Condensation	Rubber	Semi-flowable temperature-resistant sealant. Release capability.
Heat Cure	TSE3360	Heat	Rubber	General purpose adhesive / sealant with extended pot life.
		Heat	Rubber	Thermally conductive adhesive. Fast cure at elevated temperatures.
1 TSE326N	M-EX in Europe and the A	Americas		

	Performance Proc								
Flowability	Flame Retardancy	Low Volatility	Thermally Conductive	High Temp. Resistance	Low Temp. Resistance	FDA Compliant	MIL-Spec	Product Detail	
Non-flowable	UL94 V-0							P. 13	
Non-flowable	UL94 HB						MIL-A-46146B	P. 13	
Non-flowable								P. 13	
Semi-flowable	UL94 V-0							P. 14	
Non-flowable	UL94 V-0							P. 13	
Non-flowable		•						P. 13	
Non-flowable	UL94 V-0	•	•					P. 13	
Flowable			•					P. 14	
Semi-flowable	UL94 V-0	•						P. 14	
Flowable	UL94 HB	•						P. 14	
Flowable								P. 14	
Flowable	UL94 HB	•		•				P. 14	
Non-flowable	UL94 HB	•	•					P. 13	
Non-flowable				•				P. 16	
Non-flowable						•	MIL-A-46106B	P. 17	
Non-flowable				•		•	MIL-A-46106B	P. 17	
Flowable				•		•	MIL-A-46106B	P. 17	
Non-flowable								P. 17	
Non-flowable				•				P. 17	
Non-flowable								P. 17	
Non-flowable	UL94 HB							P. 15	
Non-flowable				•				P. 16	
Semi-flowable	UL94 V-1		•					P. 16	
Non-flowable	UL94 V-0							P. 16	
Flowable								P. 16	
Flowable				•				P. 16	
Flowable								P. 16	
Semi-flowable								P. 18	
Flowable								P. 18	
Flowable								P. 19	
Semi-flowable	UL94 HB							P. 18	
Flowable	UL94 HB			•				P. 19	
Flowable				•				P. 18	
Flowable				•				P. 20	
Flowable			•					P. 19	
Flowable			•					P. 19	
Non-flowable								P. 18	
Non-flowable								P. 18	
Non-flowable					•			P. 21	
Semi-flowable				•				P. 21	
Non-flowable								P. 23	
Flowable			•					P. 23	

Product Overview: Coating Materials

Туре	Grade	Cure Chemistry	Cured Property	Feature	
	ECC3010	Alkoxy	Rubber	Fast cure conformal coating material. Solvent free	
	ECC3050S	Alkoxy	Rubber	Fast cure conformal coating material. Low volatile. Solvent free	
	ECS0600	Alkoxy	Rubber	High purity repairable electrode coating. Fast tack.	
	ECS0601	Alkoxy	Rubber	High purity, non-repairable type electrode coating. UL certified.	
	ECS0609FR	Alkoxy	Rubber	High purity, non-repairable type electrode coating. UL certified.	
Part Condensation Cure	RTV160	Alkoxy	Rubber	UL certified flowable sealant.	
크	TSE3941M	Alkoxy	Rubber	Fast tack, thermally conductive flowable sealant.	
\mathcal{C}	TSE3944	Alkoxy	Rubber	Low volatile, UL certified flowable sealant.	
nc	TN3305	Alkoxy	Rubber	Fast tack, low volatile flowable adhesive / sealant. UL certified.	
<u> </u>	TSE3971	Alkoxy	Rubber	Flowable sealant.	
ISA	TSE3976-B	Alkoxy	Rubber	Low volatile, temperature resistant sealant. UL certified.	
ö	TSE398	Alkoxy	Rubber	Pourable coating / encapsulant.	
n	TN3705	Alkoxy	Rubber	Low volatile, low viscosity coating / potting material	
	XE11-A5133S	Alkoxy	Rubber	Low volatile, UL certified, thermally conductive coating & potting.	
<u>a</u>	RTV110 series	Acetoxy	Rubber	General purpose coating / encapsulant. FDA, USDA, and NSF compliant. Mil Spec.	
	TSE387	Oxime	Rubber	General purpose flowable sealant / coating.	
	TSE3877-B	Oxime	Rubber	Flowable sealant for high-temperature applications.	
T T	TSE388	Oxime	Rubber	Flowable, general purpose sealant / coating.	
	TSE389	Oxime	Rubber	Flowable, UL certified coating / sealant.	
	ECC4865	Heat	Rubber	Extreme low viscosity coating material with UV tracer.	
	TSE3221S	Heat	Rubber	Flowable sealant / coating material.	
<u> </u>	TSE325	Heat	Rubber	Flowable coating / encapsulant.	
മ്	TSE3250	Heat	Rubber	Flowable coating / encapsulant.	
_	TSE3251	Heat	Rubber	Flowable coating material.	
j	TSE3251-C	Heat	Rubber	Flowable coating material.	
21 (TSE325-B	Heat	Rubber	Flowable coating / encapsulant.	
Part Heat Cure	TSJ3155	Heat	Rubber	High purity JCR-grade white rubber.	
ক	TSJ3195-W	Heat	Gel	High purity JCR-grade white gel.	
	TSJ3185	Heat	Gel	High purity JCR-grade translucent gel.	
	TSJ3187	Heat	Gel	High purity JCR-grade translucent gel.	
2P RT		Condensation	Rubber	General purpose encapsulation and potting. FDA compliant.	
	TSE3033	Heat	Rubber	Transparent coating / encapsulant. Fast cure at elevated temperatures.	
$\sim -N$	TSE3331	Heat	Rubber	UL certified, thermally conductive, coating / encapsulant.	
542	TSE3331K ¹	Heat	Rubber	Low viscosity variant of TSE3331.	
2 Part Heat Cure	TSE3331K EX ¹	Heat	Rubber	Low viscosity variant of TSE3331.	
	XE14-B5778	Heat	Rubber	High purity JCR-grade translucent rubber.	
	TSJ3175	Heat	Gel	High purity JCR-grade thixotropic gel.	

¹ TSE3331K for Asia Pacific, TSE3331K EX for Europe and the Americas

Grease - l	Product Index		Product			
Grade Feature		Thermally Conductive	Low Bleed	Low Volatility	Heat Resistant	Detail
TSK5303	Moderate thermal conductivity with heat resistance.	•		•	•	P. 28
TSK5370	General electrical insulation. Swell resistant on silicone.			•		P. 28
TSK550	General electrical insulation, arc resistance.					P. 28
TSK551	Insulator protection from salt, dust.					P. 28
YG6111	Moderate thermal conductivity.	•		•		P. 28
YG6240	Moderate thermal conductivity, low-bleed performance.	•	•	•		P. 28
YG6260	Moderate thermal conductivity.	•		•		P. 28
TIG1000	High thermal conductivity.	•		•		P. 28

Performance								Product
Flowability	Flame Retardancy	Low Volatility	Thermally Conductive	High Temp. Resistance	JCR Grade	FDA Compliant	MIL-Spec	Detail
Flowable								P. 15
Flowable		•						P. 15
Flowable		•						P. 15
Flowable	UL94 HB	•						P. 15
Flowable	UL94 V-0	•						P. 14
Flowable	UL94 HB							P. 14
Flowable			•					P. 14
Semi-flowable	UL94 V-0	•						P. 14
Flowable	UL94 HB	•						P. 14
Flowable								P. 14
Flowable	UL94 HB	•		•				P. 14
Flowable								P. 15
Flowable		•						P. 15
Flowable	UL94 V-1	•	•					P. 14
Flowable						•	MIL-A-46106B	P. 17
Flowable								P. 16
Flowable				•				P. 16
Flowable								P. 16
Flowable	UL94 HB							P. 16
Flowable								P. 20
Flowable								P. 19
Flowable								P. 20
Flowable								P. 20
Semi-flowable								P. 20
Semi-flowable								P. 20
Flowable								P. 20
Semi-flowable					•			P. 27
Semi-flowable					•			P. 27
Semi-flowable					•			P. 27
Semi-flowable					•			P. 27
Flowable						•		P. 22
Flowable								P. 24
Flowable	UL94 V-0		•					P. 24
Flowable	UL94 V-0		•					P. 24
Flowable	UL94 V-0		•					P. 24
Semi-flowable					•			P. 27
Semi-flowable					•			P. 27

Product Overview: Encapsulants and Potting Materials

Туре	Grade	Cure Chemistry	Cured Property	Feature	
	RTV160	Alkoxy	Rubber	UL certified flowable encapsulant.	
ŏ,	TSE398	Alkoxy	Rubber	Pourable coating / encapsulant.	
70 P	TN3705	Alkoxy	Rubber	Low volatile, low viscosity potting / coating material.	
d. C	XE11-A5133S	Alkoxy	Rubber	Low volatile, UL certified, thermally conductive coating & potting.	
1 Part Cond. Cure	RTV110 series	Acetoxy	Rubber	General purpose coating / encapsulant. FDA, USDA, and NSF compliant. Mil Spec.	
(D	RTV116	Acetoxy	Rubber	Temperature-resistant flowable sealant. FDA, USDA, and NSF compliant. Mil Spec.	
	TSE325	Heat	Rubber	Flowable coating / encapsulant.	
	TSE3250	Heat	Rubber	Flowable coating / encapsulant.	
art H Cure	TSE325-B	Heat	Rubber	Flowable coating / encapsulant.	
T 6	TSE3051	Heat	Gel	Low viscosity potting gel.	
Part Heat Cure	TSE3051-FR	Heat	Gel	UL certified variant of TSE3051.	
	TSE3051-L	Heat	Gel	Low penetration variant of TSE3051.	
	RTV11	Condensation	Rubber	General purpose encapsulation and potting. FDA compliant.	
	RTV31	Condensation Rubber High temperature resistant potting. Good release properties.			
Part Roo emp. Cu	RTV566	Condensation	Rubber	Low volatile, high-low temperature-resistance.	
	RTV60	Condensation	Rubber	Extreme high temperature-resistant coating / potting. Release capability.	
	TSE3663	Condensation	Rubber	Flowable encapsulant / potting material.	
are on	TSE3661	Condensation	Rubber	Flowable encapsulant / potting material.	
	TSE3664K	Condensation	Rubber	UL certified, flowable encapsulant / potting material.	
	RTV615	Heat	Rubber	High strength potting material. Fast cure at elevated temperatures.	
	TSE3032	Heat	Rubber	Transparent potting / encapsulant with excellent release properties.	
	TSE3033	Heat	Rubber	Low viscosity, transparent potting material. Fast cure at elevated temperatures.	
	TSE3331	Heat	Rubber	UL certified, thermally conductive, coating / encapsulant.	
N	TSE3331K ¹	Heat	Rubber	Low viscosity variant of TSE3331.	
	TSE3331K EX ¹	Heat	Rubber	Low viscosity variant of TSE3331.	
Part Heat Cure	TSE3431	Heat	Rubber	UL certified, thermally conductive potting material. Release capability.	
I	TSE3431-H	Heat	Rubber	UL certified, thermally conductive potting material. Release capability.	
e <u>a</u>	XE14-B7892	Heat	Rubber	UL certified low-viscosity potting material. Low temperture cure. Release capability.	
\overline{C}	YE5822	Heat	Rubber	Low viscosity potting material. Good release properties.	
Ĭ,	FRV138	Heat	Rubber	Soft fluorosilicone encapsulant.	
(D	TIA216G	Heat	Rubber	Thermally conductive, low temperature / fast cure soft pottant.	
	TIA222G	Heat	Rubber	Thermally conductive, low temperature / fast cure soft pottant. UL certified.	
	RTV6136-D1	Heat	Gel	Low viscosity potting gel with fast cure at low temperatures.	
	TSE3062	Heat	Gel	Fast cure at low temperatures.	
	TSE3070	Heat	Gel	High-elongation gel with low temperature cure.	

¹ TSE3331K for Asia Pacific, TSE3331K EX for Europe and the Americas

Performance								Product
Flowability	Flame Retardancy	Low Volatility	Thermally Conductive	High Temp. Resistance	Low Temp. Resistance	FDA Compliant	MIL-Spec	Detail
Flowable	UL94 HB							P. 14
Flowable								P. 15
Flowable		•						P. 15
Flowable	UL94 V-1	•	•					P. 14
Flowable						•	MIL-A-46106B	P. 17
Flowable				•		•	MIL-A-46106B	P. 17
Flowable								P. 20
Flowable								P. 20
Flowable								P. 20
Flowable								P. 25
Flowable	UL94 V-1							P. 25
Flowable								P. 25
Flowable						•		P. 22
Flowable				•				P. 22
Flowable		•		•	•			P. 21
Flowable				•				P. 21
Flowable								P. 22
Flowable	UL94 HB							P. 22
Flowable	UL94 V-0							P. 22
Flowable						•		P. 23
Flowable								P. 23
Flowable								P. 24
Flowable	UL94 V-0		•					P. 24
Flowable	UL94 V-0		•					P. 24
Flowable	UL94 V-0		•					P. 24
Flowable	UL94 V-0		•					P. 24
Flowable	UL94 V-0		•					P. 24
Flowable	UL94 V-0							P. 24
Flowable								P. 24
Flowable								P. 23
Flowable		•	•					P. 23
Flowable	UL94 V-0	•	•					P. 23
Flowable								P. 26
Flowable								P. 26
Flowable								P. 26

Selection Guide

1 Part Grades BLACK=Rubber RED=Gels Alkoxy Acetoxy Oxime Heat									
Vicesity	Performance								
Viscosity Range	Thermally Conductive	Low Volatility	UL Certified	Temp. Resistant	FDA Compliant	General Purpose			
Non- Flowable	TN3085 XE11-B5320	TN3005 TN3085 XE11-B5320	TSE3854DS TN3085 RTV133 RTV167 TSE382 TSE384-B	FRV1106 RTV106 TSE3826	RTV100 RTV106	TSE385 RTV157 TSE370 XE13-B3208			
High Viscosity	TSE3843-W	TSE3976-B	TSE3853-W TSE3976-B TSE3843-W	TSE3976-B RTV159 TSE3877-B		TSE3971 TSE3212 TSE322			
Medium Viscosity	TSE3941M XE11-A5133S	TSE3944 XE11-A5133S TN3305	TSE3944 XE11-A5133S RTV160 TN3305 RTV110	RTV116	RTV110 RTV116	TSE398			
	TSE3280-G TSE3281-G		TSE322S TSE325	TSE326 TSE3261-G TSE326M		TSE387 TSE388 TSE3221S			
		ECC3050S ECS0600 ECS0601 ECS0609FR TN3705	ECS0601 ECS0609FR			ECC3010			
Low Viscosity			TSE3051FR			TSE3051 TSE3051-L TSE325 TSE3250 TSE3251 TSE3251-C TSE325-B			

Cure System Performance Guide

_						
Attribute	Alko	ху	Acetoxy	Oxime	Heat Cure	
Attribute	Fast Cure	Slow Cure	Acetoxy	Oxime		
Cure Byproduct	Alcohol	Alcohol	Acetic Acid	Methylethyl Ketoxime	None	
Cure Speed	Fast	Slow	Fast	Moderate	Very Fast	
Corrosion on Copper	None	None	Yes	Yes	None	
Corrosion on Metals	None	None	Yes	None	None	
Odor	Low	Low	Strong	Low	None	
Strength	Good	Good	Very Strong	Good	Good	

Viscosity	Performance							
Range	Thermally Conductive	Low Volatility	UL Certified	Temp. Resistant	FDA Compliant	General Purpose		
Non-Flowable						TSE3360		
High Viscosity				RTV577 RTV88				
Medium Viscosity	TSE3380	RTV566		RTV31 RTV566 RTV60	RTV11			
Low Viscosity	TSE3331 TSE3331K TSE3431 TSE3431-H TIA222G TIA216G	TIA222G TIA216G	TSE3331 TSE3331K TSE3431 TSE3431-H XE14-B7892 TIA222G		RTV615	RTV6136-D1 TSE3032 TSE3033 TSE3062 TSE3070 TSE3330 YE5822		
			TSE3661 TSE3664K			TSE3663		



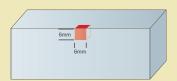
Viscosity and flowability of the silicone material are often key factors in the selection of a material for use in sealing, coating, and encapsulation / potting applications. A broad array of material performance and viscosity combinations are provided to help match the requirements of many applications.

Application Geometry and Cure Chemistry Options

The shape and conditions of the part are important in selecting the suitable silicone grade for each application.

The following are some general guidelines:

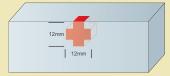
Shallow Cavity / Small Mass



Selection Options:

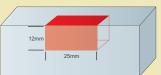
- 1 Part Condensation Cure
- 1 Part Heat Cure
- 2 Part Room Temp. Cure
- 2 Part Heat Cure

Complex Design - Exposed Surface



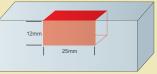
- 1 Part Heat Cure 2 Part Room Temp. Cure

Deep Cavity / Large Mass



Selection Options:

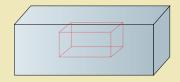
- 2 Part Heat Cure



Selection Options:

- 1 Part Heat Cure
- 2 Part Room Temp. Cure
- 2 Part Heat Cure

Enclosed System



Selection Options:

- 1 Part Heat Cure 2 Part Heat Cure

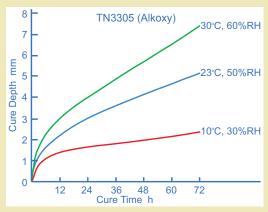
Product Details - 1 Part Condensation Cure Grades

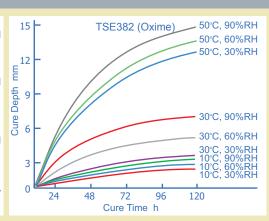
Pro	perties		RTV167	RTV133	TSE385	TSE3854DS	TN3005	TN3085	XE11-B5320
Cure	Chemistry		Alkoxy	Alkoxy	Alkoxy	Alkoxy	Alkoxy	Alkoxy	Alkoxy
Flow	ability		Non-Flowable	Non-Flowable	Non-Flowable	Non-Flowable	Non-Flowable	Non-Flowable	Non-Flowable
Feat	ures and Benefits		High strength, paste adhesive with MILA- 46106B and UL certified	UL certified paste adhesive.	Paste adhesive	Paste adhesive. UL certified	Fast tack, low volatile paste adhesive.	Fast tack, low volatile paste adhesive. UL certified	Fast tack, low volatile, thermally conductive paste adhesive. UL certified
App	Adhesive / Sealant		•	•	•	•	•	•	•
Application	Coating								
tion	Encapsulant / Potting	9							
Visco	osity (23°C)	Pa.s (P)	-	-	-	-	-	-	-
Appl	ication Rate	g/min	180	650	-	-	-	-	-
Tack	Free Time	min	240	60	90	15	7	7	5
Spec	cific Gravity (23°C)		1.12	1.23	1.10	1.33	1.04	1.63	2.59
Harc	Iness		37	46	35	45	22	46	80
Tens	ile Strength	MPa (psi)	5.5 (800)	4.5 (650)	2.9 (420)	3.0 (435)	1.8 (260)	2.3 (335)	3.6 (520)
Elon	gation	%	600	250	390	300	330	150	40
Adh	esive Strength	MPa (psi)	1.2 (175)	-	2.0 (290)	2.2 (320)	1.2 (175)	1.3 (190)	1.3 (190)
Thermal Conductivity W/m·K		-	-	0.17	0.34	0.18	0.7	1.3	
Volu	me Resistivity	MΩ·m	3.0x10 ⁷	3.0x10 ⁷	5.0x10 ⁷	2.0x10 ⁶	2.0x10 ⁷	4.0x10 ⁶	2.0x10 ⁷
Diele	ectric Strength	kV/mm	20	20	22	25	26	23	17
Diele	ectric Constant (60Hz)		2.8	2.8 (100Hz)	3.0	3.1	2.7	4.0	2.6
Dissi	pation Factor (60Hz)		0.0026	0.001 (100Hz)	0.001	0.02	0.002	0.04	0.005
Low	Molecular Siloxane (D4-D10) wt%	-	-	-	-	0.01	0.01	0.010
Flam	ne Retardancy		UL94 HB	UL94 V-0		UL94 V-0		UL94 V-0	UL94 HB
Low	Volatility						•	•	•
Tem	perature Resistance								
Ther	mally Conductive							•	•
FDA									
MIL-	Spec ³		MIL-A-46106B ⁴						
	White								
C	Clear								
olor	Black			•			•		
	Gray		•					•	
	Tube		•		•	•		•	
Pa	Cartridge		•	•	•	•		•	•
Packaging	Can								
ging	Pail								
	See Page 15 for deta	ails					•		

UIS K 6249 ² ASTM D2196 ³ Testing is performed in accordance with current Momentive Performance Materials quality test methods, laboratory conditions, procedures, frequency and sampling. ⁴ MIL-A-46106B Group I Type I

Cure Properties:

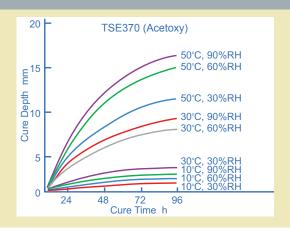
Condensation cure grades cure with exposure to atmospheric moisture. The cure process begins from the outer surface and proceeds inward. Therefore, deep section curing (in excess of 6mm) is not recommended. Typically, tackfree is achieved in 5-60 minutes at 25°C, 50%RH, depending on the grade.



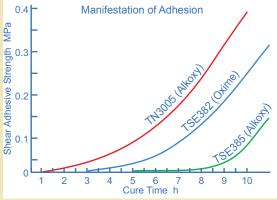


TSE3944	TSE3853-W	TSE3971	TSE3976-B	XE11-A5133S	TSE3941M	TN3305	RTV160	ECS0609FR
Alkoxy	Alkoxy	Alkoxy	Alkoxy	Alkoxy	Alkoxy	Alkoxy	Alkoxy	Alkoxy
Semi-Flowable	Semi-Flowable	Flowable	Flowable	Flowable	Flowable	Flowable	Flowable	Flowable
Flowable low volatile adhesive / sealant. UL certified	Flowable adhesive / sealant. UL certified	Flowable adhesive / sealant.	Flowable, high-temperature resistant low volatile adhesive / sealant. UL certified	Flowable, low volatile thermally conductive potting / coating material. UL certified	Fast tack, thermally conductive flowable adhesive / sealant.	Fast tack, low volatile, flowable adhesive / sealant.	Flowable adhesive. UL certified	High-purity electrode coating material with fast tack performance. UL certified
•	•	•	•		•	•		
•		•	•	•	•	•	•	•
				•			•	
-	400 (4000) 1	100 (1000) ¹	100 (1000) 1	60 (600) ¹	50 (500) ¹	47 (470) ¹	38 (380) ²	18 (180) ¹
-	-	-	-	-	-	-	-	-
5	15	10	5	10	5	9	240	7
1.31	1.31	1.04	1.08	1.64	1.64	1.04	1.04	1.22
38	34	16	30	63	63	14	25	28
1.5 (220)	2.3 (335)	1.5 (220)	1.7 (245)	3.9 (565)	3.2 (465)	1.5 (220)	1.9 (275)	2.4 (350)
170	270	350	210	100	70	400	230	250
1.0 (145)	1.3 (190)	1.1 (160)	1.3 (190)	1.3 (190)	1.4 (205)	1.0 (145)	-	1.2 (175)
0.36	0.34	0.18	0.18	0.83	0.83	0.18	-	-
1.0x10 ⁷	2.0x10 ⁶	$2.0x10^{7}$	1.0x10 ⁷	4.0x10 ⁶	4.0x10 ⁶	$2.0x10^{7}$	4.0x10 ⁶	1.0x10 ⁵
22	20	21	20	20	21	26	20	20
3.8	3.1	2.9	3.5	4.0	4.0	2.7	2.8	3.1
0.02	0.02	0.005	0.01	0.04	0.04	0.002	0.001	0.05
0.028	-	-	0.025	0.025	-	0.01	-	-
UL94 V-0	UL94 V-0		UL94 HB	UL94 V-1		UL94 HB	UL94 HB	UL94 V-0
•			•	•		•		•
			•					
				•	•			
		•	•			•		
•								•
•	•	•	•	•	•			
•	•	•	•	•	•		•	•
					•			
						•		

Typical property data values should not be used as specifications



Adhesion is typicaly achieved after 5-15 hours. Full material properties including electronic performance, is achieved in up to 7 days.



Product Details - 1 Part Condensation Cure Grades

Pro	perties		TSE398	ECS0600	TN3705	ECS0601	ECC3050S	ECC3010	TSE382	
Cure	e Chemistry		Alkoxy	Alkoxy	Alkoxy	Alkoxy	Alkoxy	Alkoxy	Oxime	
Flow	vability		Flowable	Flowable	Flowable	Flowable	Flowable	Flowable	Non-Flowable	
Feat	rures and Benefits		Flowable adhesive / sealant.	High-purity electrode coating material with fast tack performance. Repairable type	Low volatile potting and coating material	High-purity electrode coating material with fast tack performance	Fast cure conformal coating material. Low volatile. Solvent free	Fast cure conformal coating material. Solvent free	General purpose paste adhesive. UL certified	
App	Adhesive / Sealant								•	
Application	Coating		•	•	•	•	•	•		
ion	Encapsulant / Potting	g	•		•					
Visc	osity (23°C)	Pa.s (P)	17 (170) 1	5.0 (50) 1	1.5 (15) 1	1.4 (14) 1	0.55 (5.5) 1	0.11 (1.1) 1	-	
Appl	lication Rate	g/min	-	-	-	-	-	-	-	
Tack	Free Time	min	10	7	7	7	5	3	10	
Spec	cific Gravity (23°C)		1.04	1.03	1.01	1.01	0.98	0.99	1.04	
Harc	dness		14	20	13	25	22	35	28	
Tens	sile Strength	MPa (psi)	1.3 (190)	1.2 (175)	0.4 (60)	0.8 (115)	-	-	1.9 (275)	
Elon	gation	%	230	450	130	150	-	-	380	
Adh	esive Strength	MPa (psi)	0.7 (100)	-	0.2 (30)	0.3 (45)	-	-	1.7 (245)	
Ther	rmal Conductivity	W/m·K	0.18	-	0.18	-	-	-	0.18	
Volu	me Resistivity	MΩ·m	2.0x10 ⁷	4.0x10 ⁷	2.0x10 ⁷	2.0x10 ⁷	1.0x10 ⁷	1.0x10 ⁷	1.0x10 ⁷	
Diele	ectric Strength	kV/mm	23	20	26	20	20	20	23	
Diele	ectric Constant (60Hz)		3.0	2.8	2.7	2.6	2.60	2.78	2.9	
Diss	ipation Factor (60Hz)		0.01	0.001	0.002	0.002	0.001	0.001	0.004	
Low	Molecular Siloxane (D4-D10)	wt%	-	0.01	0.01	0.01	0.01	-	-	
Flam	ne Retardancy					UL94 HB			UL94 HB	
Low	Volatility			•	•	•	•			
Tem	perature Resistance									
Ther	mally Conductive									
FDA										
MIL-	-Spec									
	White									
	Clear									
Color	Black				•	•			•	
)r	Gray								•	
	Red									
	Tube		•							
Pa	Cartridge		•	•		•				
Packaging	Can						•	•		
ging	Pail			•				•		
	See Page 15 for deta	ails			•				•	
1 110 1	K 6249									

¹JIS K 6249

Packaging Supplement

•													
Grade	Tube		С	Cartridge			Can			Pail			
Grado	W	С	В	W	С	В	G	W	С	В	W	С	В
TN3005						•							•
TN3305			•			•							•
TN3705		0	•		0	•			0	•		0	•
TSE382						•	•						
TSE387						•							
TSE389						•							

W: White, C: Clear, B: Black, G: Gray

TSE3826	TSE384-B	TSE3843-W	TSE3877-B	TSE387	TSE388	TSE389	FRV1106
Oxime	Oxime	Oxime	Oxime	Oxime	Oxime	Oxime	Acetoxy
Non-Flowable	Non-Flowable	Semi-Flowable	Flowable	Flowable	Flowable	Flowable	Non-Flowable
High temperature resistant paste adhesive	General purpose paste adhesive. UL certified	General purpose flowable adhesive / sealant. UL certified	General purpose flowable adhesive / sealant.	General purpose flowable adhesive / sealant.	General purpose flowable adhesive / sealant.	Flowable sealant / coating material. UL certified	Fluorosilicone with high temperature performance. Good fuel, oil, moisture, UV, ozone & chemical resistance
•	•	•	•	•	•		•
			•	•	•	•	
-	-	500 (5000) ¹	300 (3000) 1	60 (600) ¹	10 (100) 1	5.6 (56) ¹	-
-	-	-	-	-	-	-	88
10	60	60	20	90	60	30	20
1.04	1.46	1.57	1.08	1.03	1.04	1.04	1.58
29	50	60	25	25	16	30	42
2.0 (290)	2.9 (421)	3.9 (565)	2.0 (290)	2.3 (335)	1.5 (220)	2.0 (290)	3.33 (485)
400	270	130	440	350	330	200	230
1.4 (205)	1.4 (203)	1.8 (260)	2.0 (290)	1.3 (190)	1.3 (190)	1.8 (260)	-
0.18	0.59	0.67	0.18	0.18	0.18	0.18	-
1.0x10 ⁷	1.0x10 ⁷	1.0x10 ⁷	1.0x10 ⁷	1.0x10 ⁷	1.0x10 ⁷	1.0x10 ⁷	-
23	22	21	20	20	20	20	13.7
2.9	4.0	3.9	3.5	2.9	2.8	2.7	6.3 (1000Hz)
0.004	0.016	0.02	0.01	0.004	0.008	0.009	-
-	-	-	-	-	-	-	-
	UL94 V-0	UL94 V-1				UL94 HB	
•			•				•
		•					
	•		•	•		•	
					•		
•							•
•	•	•					
•	•	•	•		•		•
			•				
				•		•	

Typical property data values should not be used as specifications

Product Details - 1 Part Condensation Cure Grades

Pro	perties		RTV157	RTV159	RTV100 series	RTV106	TSE370	RTV116	RTV110 series
Cure	Chemistry		Acetoxy	Acetoxy	Acetoxy	Acetoxy	Acetoxy	Acetoxy	Acetoxy
Flow	ability		Non-Flowable	Non-Flowable	Non-Flowable	Non-Flowable	Non-Flowable	Flowable	Flowable
Featu	ures and Benefits		High strength paste adhesive	High temperature, high strength, paste adhesive	Paste adhesive with FDA, USDA, NSF, and MIL-A-46106B	High temperature resistant paste adhesive. FDA, USDA, NSF, MIL-A-46106B	Fast tack paste adhesive	High temperature resistant, flowable adhesive. FDA, USDA, NSF, MIL-A-47040, MIL-A-46106B	Flowable adhesive with FDA, USDA, NSF, MIL-A-46106B
Adhesive / Sealant			•	•	•	•	•	•	
Application	Coating								•
tion	Encapsulant / Pottir	ng						•	•
Visco	osity (23°C)	Pa.s (P)	-	-	-	-	-	25 (250) ¹	20 (200) 1
Appli	cation Rate	g/min	155	175	400	400	-	-	-
Tack	Free Time	min	45	45	20	20	5	30	20
Spec	ific Gravity (23°C)		1.09	1.09	1.05	1.07	1.04	1.09	1.05
Hard	ness		28	20	30	30	22	20	25
Tensi	le Strength	MPa (psi)	6.2 (900)	7.0 (1,025)	2.75 (400)	2.55 (370)	2.5 (365)	2.45 (355)	2.20 (320)
Elong	gation	%	825	350	450	400	530	350	325
Adhe	sive Strength	MPa (psi)	1.3 (183)	-	1.4 (200)	1.4 (200)	2.2 (320)	0.9 (125)	0.7 (100)
Therr	mal Conductivity	W/m·K	-	-	-	-	0.18	-	-
Volur	ne Resistivity	MΩ·m	7.5x10 ⁶	1.1x10 ⁷	3.0x10 ⁷	3.0x10 ⁶	1.0x10 ⁷	2.0x10 ⁶	6.0x10 ⁶
Diele	ctric Strength	kV/mm	20.7	19.7	20	20	22	16	16
Diele	ctric Constant (60Hz)		2.9	2.6	2.8	2.8	3.0	2.8	2.8
Dissi	oation Factor (60Hz)		0.0009	0.0007	0.001	0.001	0.003	0.001	0.001
Low N	Molecular Siloxane (D4-D10)	wt%	-	-	-	-	-	-	-
Flam	e Retardancy								
Low	Volatility								
Temp	erature Resistance			•		•		•	
Therr	mally Conductive								
FDA					•	•		•	•
MIL-S	Spec ²				MIL-A-46106B ³	MIL-A-46106B ³		MIL-A-46106B ³	MIL-A-46106B ³
	White				RTV102				RTV112
	Clear				RTV108				RTV118
Q	Black				RTV103				
Color	Gray		•						
	Red			•		•		•	
	Aluminum				RTV109				
	Tube		•	•	•	•	•	•	•
Pack	Cartridge		•	•	•	•			
Packaging	Can								
Bu	Pail		•	•	•	•		•	•
1ASTN	И D2196 ² Testing is per	formed in	accordance with co	irrent Momentive Pa	erformance Material	ls quality test method	ds Jahoratory conc	litions	

¹ASTM D2196 ²Testing is performed in accordance with current Momentive Performance Materials quality test methods, laboratory conditions, procedures, frequency and sampling ³MIL-A-46106B Group III Type I Typical property data values should not be used as specifications

Product Details - 1 Part Heat Cure Grades

Pro	perties		XE13-B3208	TSE3212	LA650S	TSE322	TSE322S	TSE3261-G
Flowa	ability		Non-Flowable	Semi-Flowable	Non-Flowable	Semi-Flowable	Semi-Flowable	Flowable
Featu	res and Benefits		Paste adhesive / sealant	Thixotropic adhesive / sealant	Non-flowable adhesive that cures to a tough silicone elastomer	Flowable adhesive / sealant	Flowable adhesive / sealant. UL certified	High temperature resistant flowable adhesive / sealant
Ąp	Adhesive / Sealant		•	•	•	•	•	•
plica	Adhesive / Sealant Coating Encapsulant / Potting							
ation	Encapsulant / Pott	ting						
Visco	sity (23°C)	Pa.s (P)	670 (6700) ¹	280 (2800) ¹	150 (1500) ¹	110 (1100) 1	70 (700) ¹	50 (500) ¹
Cure	Condition	°C/h	150/1	150/1	125/1.5	150/1	150/1	150/1
Spec	ific Gravity (23°C)		1.08	1.26	1.10	1.27	1.26	1.48
Hardı	ness		50	52	65	45	37	52
Tensi	e Strength	MPa (psi)	4.4 (640)	3.7 (535)	6.5 (950)	3.4 (495)	3.6 (520)	4.9 (710)
Elong	ation	%	430	240	120	230	230	160
Adhe	sive Strength	MPa (psi)	3.7 (535)	2.6 (375)	5.0 (730)	2.5 (365)	2.5 (365)	2.0 (290)
Therr	nal Conductivity	W/m.K	0.20	0.29	0.2	0.29	0.29	0.41
Volun	ne Resistivity	MΩ·m	1.0x10 ⁷	2.0x10 ⁷	6.0x10 ⁷	$2.0x10^{7}$	1.0x10 ⁷	2.0x10 ⁷
Diele	ctric Strength	kV/mm	23	20	22	20	25	22
Diele	ctric Constant (60Hz	z)	3.1	3.2	2.9	3.1	3.1	3.9
Dissip	oation Factor (60Hz))	0.001	0.001	0.01	0.006	0.006	0.005
Flame	e Retardancy						UL94 HB	
Temp	erature Resistance							•
Therr	Thermally Conductive							
	White							
	Clear							
Color	Black				•	•		
Ť	Gray							•
	Blue					•	•	
Т	Tube			•		•		
ack	Cartridge		•	•	•	•	•	
Packaging	Can			•		•	•	
0	Pail		•	•		•	•	•

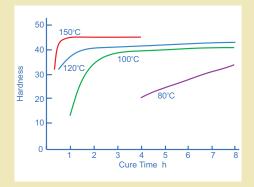
¹JIS K 6249

Typical property data values should not be used as specifications

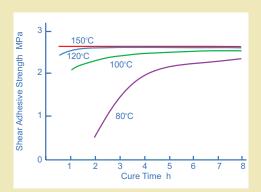
Cure Properties:

The cure performance of 1 Part Heat Cure grades is demonstrated by the relationship between temperature and hardness, and temperature and adhesive strength of TSE322 when placed in an oven at temperatures ranging from 80°C to 150°C.

Hardness & Cure Time - TSE322



Adhesion & Cure Time - TSE322



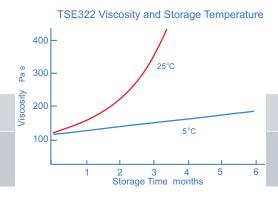
Product Details - 1 Part Heat Cure Grades

Pro	perties		TSE3280-G	TSE3281-G	TSE3221S	TSE326
Flowa	ability		Flowable	Flowable	Flowable	Flowable
Featu	res and Benefits		Thermally conductive flowable adhesive	Thermally conductive flowable adhesive	Flowable adhesive / sealant, coating material	High temperature resistant flowable adhesive. UL certified
Apl	Adhesive / Sealar	nt	•	•	•	•
Application	Coating				•	
tion	Encapsulant / Po	otting				
Visco	sity (23°C)	Pa.s (P)	60 (600) ¹	60 (600) ¹	58 (580) ¹	28 (280) ¹
Cure	Cure Condition °C/h		150/1	150/1	150/1	150/1
Spec	Specific Gravity (23°C)		2.10	2.70	1.03	1.45
Hardı	ness		62	84	28	43
Tensi	e Strength	MPa (psi)	3.2 (465)	4.5 (655)	2.8 (405)	3.4 (495)
Elonç	ation	%	110	50	370	170
Adhe	sive Strength	MPa (psi)	2.0 (290)	2.5 (365)	2.5 (365)	2.0 (290)
Therr	nal Conductivity	W/m.K	0.88	1.68	0.18	0.41
Volun	ne Resistivity	MΩ·m	2.5x10 ⁶	4.8x10 ⁶	6.0x10 ⁷	2.0x10 ⁷
Diele	ctric Strength	kV/mm	21	15	23	22
Diele	ctric Constant (60H	Hz)	4.3	5.2	2.8	3.3
Dissip	oation Factor (60Hz	z)	0.002	0.002	0.001	0.02
Flame	e Retardancy					UL94 HB
Temp	erature Resistance	e				•
Therr	nally Conductive		•	•		
	White					
	Clear					
Color	Black					
,	Gray		•	•		
	Red					•
Tube		•		•	•	
Packaging	Cartridge		•			•
agino	Can		•	•	•	•
C)	Pail		•			•

 $^1 JIS~K~6249$ $^2 ASTM~D2196$ $^3 TSE326M~EX~in~Europe~and~the~Americas.$

Storage Stability:

Storage under low temperature conditions is important particularly for 1-part heat cure grades to prevent viscosity increase.



TSE326M ³	TSE3251	TSE3251-C	TSE325	TSE325-B	TSE3250	ECC4865
Flowable	Semi-Flowable	Semi-Flowable	Flowable	Flowable	Flowable	Flowable
High temperature resistant flowable adhesive	Flowable coating material	Flowable coating material	Flowable potting / coating material	Flowable potting / coating material	Flowable potting / coating material	Low viscosity conformal coating with UV tracer, fast thermal cure & long-term viscosity stability
•						
	•	•	•	•	•	•
			•	•	•	
16 (160) ¹	8.5 (85) ¹	7.0 (70) ¹	4.0 (40) 1	3.5 (35) 1	1.3 (13) ¹	0.25 (2.5) 2
200/0.5	150/1	150/1	150/1	150/1	150/1	-
1.46	1.02	1.02	1.02	1.02	0.97	1.19
38	16	16	12	20	9	35
2.9 (420)	0.7 (100)	0.7 (100)	0.7 (100)	0.9 (130)	-	-
180	200	200	200	200	-	-
1.5 (220)	0.4 (60)	0.4 (60)	0.4 (60)	0.4 (60)	0.1 (15)	-
0.41	0.18	0.18	0.18	0.18	0.17	-
2.0x10 ⁷	2.0x10 ⁷	2.0x10 ⁷	2.0x10 ⁷	2.0x10 ⁷	2.0x10 ⁷	-
22	20	20	21	21	21	20
3.3	2.8	2.8	2.9	2.9	2.8	2.4
0.02	0.002	0.001	0.001	0.001	0.001	0.01
•						
				•		
•						
•	•	•	•	•	•	
			•			•

Typical property data values should not be used as specifications

Product Details - 2 Part Room Temperature Cure Grades

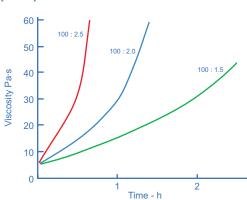
Pro	perties		RTV577	rtv8	88	RT\	/60	RTV566
Com	oonents		RTV577 ³ DB	T RTV88 ³	DBT	RTV60 ³	DBT	RTV566(A)3 RTV566(B)
Flowa	ability		Non-Flowab	ole Semi-Flov	vable	Flow	able	Flowable
Featu	res and Benefits		Low temperaturesistant paste sealant with good release capabilit	resistant, semi- od sealant. Go	High temperature resistant, semi-flowable sealant. Good release capabilities		perature flowable ith good pabilities	Low volatile, low out gassing sealant with Lov and High temperature performance capability
App	Adhesive / Sealant Coating Encapsulant / Potting		•	•				
licat	Coating							
ion	Encapsulant / Pott	ting			•)	•	
Mixin	Mixing Ratio ((A):(B) by weight)		100:0.5	100:0	100:0.5		0.5	100:0.1
Color	Color (mixed)		White	Red	Red		ed	Red
Visco	sity (mixed) (23°C)	Pa.s (P)	700 (7000)	880 (880	00) 2	47 (4	70) ²	43 (430) 2
Pot L	ife (23°C)	h	2	0.75	;	2		1.5
Cure	Condition	°C/h	25/24	25/24	4	25/24		25/24
Spec	fic Gravity (23°C)		1.35	1.47	1.47 1.48		18	1.49
Hardı	ness		48	58	58		7	61
Tensi	e Strength	MPa (psi)	3.0 (440)	5.8 (84	840) 6.9 (995		995)	5.5 (795)
Elong	ation	%	150	120		12	.0	120
Adhe	sive Strength	MPa (psi)	-	-		-		3.2 (465)
Therr	nal Conductivity	W/m·K	0.31	0.31		0.0	31	0.31
/olun	ne Resistivity	MΩ·m	5.6x10 ⁶	2.8x10	O ⁶	4.4x	10 ⁶	2.0x10 ⁶
Diele	ctric Strength	kV/mm	18.5	17.4		17	.7	21.2
Diele	ctric Constant (60Hz	<u>z</u>)	3.98 (1kH	z) 4.3 (1kl	Hz)	4.0 (1	kHz)	3.9 (1kHz)
Dissip	pation Factor (60Hz)		0.02 (1kH	z) 0.03 (1k	(Hz)	0.02 (1 kHz)	0.02 (1kHz)
-lame	ongation % dhesive Strength MPa (p mermal Conductivity W/m-K plume Resistivity MΩ-m ielectric Strength kV/mm ielectric Constant (60Hz) issipation Factor (60Hz) ame Retardancy bw Volatility							
_ow '	/olatility							•
emp	erature Resistance		•	•		•	•	•
DA								
,D	Bottle							
acka	Can							
Packaging	Pail							
<u>O</u>	Kit		•	•		•	1	•

¹JIS K 6249 ²ASTM D2196 ³Sub-Zero long-term storage required.

Cure Speed:

The cure speed of 2 Part Condensation Cure grades can be changed by adjusting the amount of the catalyst component. However, the post-cure properties of the material may vary from those achieved under standard mixing ratios, and therefore adequate testing and confirmation prior to use in an application is required.

TSE3663 - Mixing Ratios & Viscosity (23°C)



RTV31	RTV11	TSE3663	TSE3661	TSE3664K
RTV31 ³ DBT	RTV11 ³ DBT	TSE3663(A) TSE3663(B)	TSE3661(A) TSE3661(C)	TSE3664(A) TSE3664(B)
Flowable	Flowable	Flowable	Flowable	Flowable
High temperature resistant flowable sealant with good release capabilities	Sealant with good release properties. FDA compliance	Flowable encapsulant / adhesive	Flowable encapsulant / adhesive with fast tack free times. UL certified	Flowable encapsulant / adhesive with fast tack free times. UL certified
	•			
•	•	•	•	•
100:0.5	100:0.5	100:2	100:3	100:7.5
Red	White	Off-White	Blue Green	Gray
25 (250) ²	11 (110) 2	4.0 (40) ¹	3.5 (35) ¹	3.0 (30) ¹
2	1.5	0.5	0.1	0.1
25/24	25/24	23/72	23/72	23/72
1.42	1.19	1.19	1.20	1.41
54	41	42	30	60
5.9 (870)	2.1 (300)	1.4 (205)	1.1 (160)	3.0 (435)
170	160	110	120	70
-	-	0.9 (130)	0.8 (115)	1.0 (145)
0.31	0.29	0.27	-	0.42
1.6x10 ⁶	1.1x10 ⁷	1.0x10 ⁷	1.0x10 ⁷	5.0x10 ⁷
17	20.3	20	20	26
4.4 (1kHz)	3.3 (1kHz)	3.1	3.2	3.1
0.03 (1kHz)	0.006 (1kHz)	0.025	0.02	0.01
			UL94 HB	UL94 V-0
•				
	•			
		•	•	•
		•	•	•
		•	•	•
•	•		ifications	

Typical property data values should not be used as specifications

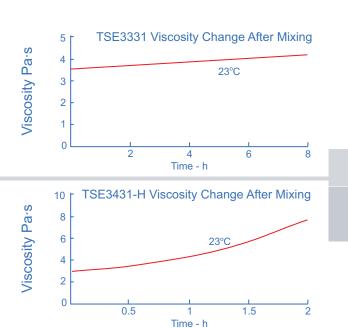
Product Details - 2 Part Heat Cure Grades

Pro	perties		TSE3360	TSE3380	TIA222G	FRV138	TIA216G	RTV615	TSE3032	
Com	ponents		TSE3360(A) TSE3360(B)	TSE3380(A) TSE3380(B)	TIA222G(A) TIA222G(B)	FRV138(A) FRV138(B)	TIA216G(A) TIA216G(B)	RTV615(A) RTV615(B)	TSE3032(A) TSE3032(B)	
Flowa	ability		Non-Flowable	Flowable	Flowable	Flowable	Flowable	Flowable	Flowable	
Featu	ures and Benefits		General purpose paste adhesive with extended pot life	Thermally conductive adhesive	Thermally conductive, low temperature/fast cure, UL certified	Fluorosilicone encapsulant	Thermally conductive, low temperature/fast cure	Low viscosity encapsulant / potting material with capability to cure at RT. FDA recognition	Transparent encapsulant / potting material with good release properties	
Adhesive / Sealant		•	•							
Adhesive / Sealant Coating Encapsulant / Potting										
Encapsulant / Potting				•	•	•	•	•		
Mixing Ratio ((A):(B) by weight)		100:100	100:100	100:100	100:100	100:100	100:10	100:10		
Color (mixed)		White	Gray	Gray	Translucent	Gray	Transparent	Transparent		
Visco	Viscosity (mixed) (23°C) Pa.s (P)		640 (6400) ¹	40 (400) 1	20 (200) 1	13 (130)	8 (80) 1	4.0 (40) 2	4.0 (40) 1	
Pot Li	Pot Life (23°C)		24	8	4	8	0.5	4	4	
Cure	Condition	°C/h	150/1	150/0.5	70/0.5	150/1	70/0.5	150/0.25	100/1	
Spec	ific Gravity (23°C)		1.12	2.70	2.81	1.3	2.69	1.02	1.02	
Hardı	ness		42	70	45 (type E)	55 (shore 00)	45 (type E)	44	35	
Tensil	e Strength	MPa (psi)	5.4 (785)	2.5 (365)	0.3 (44)	0.3 (44)	0.2 (29)	6.3 (920)	4.5 (655)	
Elong	ation	%	380	100	40	73	40	120	210	
Adhe	sive Strength	MPa (psi)	3.1 (450)	1.5 (220)	-	-	-	-	-	
Thern	nal Conductivity	W/m·K	0.23	1.68	2.1	-	1.6	0.19	0.17	
Volum	ne Resistivity	MΩ·m	1.0x10 ⁷	2.1x10 ⁶	4.8x10 ⁶	1.6x10 ²	4.8x10 ⁶	1.8x10 ⁷	2.0x10 ⁷	
Dielec	ctric Strength	kV/mm	21	15	20	-	18	19.7	21	
Diele	ctric Constant (60Hz	<u>:</u>)	3.0	5.7	5.3	7.2	5.0	2.7 (1kHz)	2.8	
Dissip	oation Factor (60Hz)		0.001	0.002	0.002	-	0.002	0.0006 (1kHz)	0.001	
Low N	Molecular Siloxane (D4-D1)) wt%			0.02		0.02			
Flame	e Retardancy				UL94 V-0					
Therr	Thermally Conductive			•	•		•			
FDA	FDA							•		
	Bottle								•	
ack	Can				• •		• •		•	
Packaging	Pail		• •	• •	• •		• •		•	
Q	Kit 2ASTM D219			Furone and the Ame		EX unavailable in As		•		

¹JIS K 6249 ²ASTM D2196 ³TSE3331K unavailable in Europe and the Americas ⁴TSE3331K EX unavailable in Asia

Pot Life:

The pot life of a 2 Part Heat Cure grade is affected by changes in viscosity that occur after the components have been mixed.

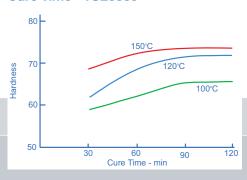


TSE3331	TSE3431	TSE3331K EX⁴	TSE3331K ³	TSE3431-H	XE14-B7892	YE5822	TSE3033
TSE3331(A) TSE3331(B)	TSE3431(A) TSE3431(B)	TSE3331KEX(A) TSE3331KEX(B)	TSE3331K(A) TSE3331K(B)	TSE3431-H(A) TSE3431-H(B)	XE14-B7892(A) XE14-B7892(B)	YE5822(A) YE5822(A)	TSE3033(A) TSE3033(B
Flowable	Flowable	Flowable	Flowable	Flowable	Flowable	Flowable	Flowable
Thermally conductive encapsulant / potting material. UL certified	Encapsulant / potting material with UL certified, thermal conductivity, and good release properties	1	Thermally conductive encapsulant / potting material. UL certified	Encapsulant / potting material with UL certified, thermal conductivity, and good release properties	Encapsulant / potting material with UL certified, low temperature cure, and good release properties	Low viscosity transparent encapsulant / potting material. Good release properties	Low viscosity transparent encapsulant / potting material
•		•	•				•
•	•	•	•	•	•	•	•
100:100	100:10	100:100	100:100	100:10	100:100	100:10	100:100
Gray	Black	Dark Gray	Dark Gray	Black	Black	Transparent	Transparent
3.5 (35) 1	3.3 (33) 1	3.0 (30) 1	2.6 (26) ¹	2.6 (26) ¹	1.3 (13) 1	1.0 (10) 1	0.9 (9) 1
8	1.5	8	8	1.5	2	4	6
120/1	100/1	120/1	120/1	100/1	60/1	100/1	150/0.5
1.51	1.50	1.43	1.43	1.52	1.39	0.97	1.01
60	70	50	45	70	60	27	30
2.9 (420)	4.9 (710)	3.0 (440)	3.1 (450)	4.1 (595)	3.5 (510)	0.4 (58)	1.0 (145)
70	70	100	120	60	100	130	130
1.3 (190)	-	1.6 (230)	1.6 (230)	-	-	-	0.3 (44)
0.63	0.63	0.53	0.53	0.63	0.44	0.17	0.17
2.0x10 ⁶	5.0x10 ⁷	6.0x10 ⁶	6.0x10 ⁶	5.0x10 ⁶	2.0x10 ⁷	2.0x10 ⁷	2.0x10 ⁷
26	26	22	22	27	27	21	21
3.4	3.4	3.1	3.1	3.5	3.1	2.8	2.8
0.017	0.014	0.015	0.015	0.014	0.01	0.001	0.001
UL94 V-0	UL94 V-0	UL94 V-0	UL94 V-0	UL94 V-0	UL94 V-0		
•	•	•	•	•			
	•			•		•	
• •	• •	• •	• •	• •	• •	•	• •
• •	•			•	• •		• •

Cure Properties:

The cure performance of 2 Part Heat Cure grades is demonstrated by the relationship between temperature and hardness of TSE3380 when placed in an oven at temperatures ranging from 100°C to 150°C.

Hardness & Cure Time - TSE3380



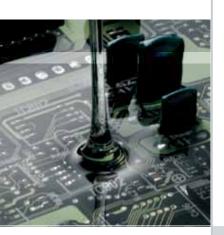
Product Details - 1 Part Gels

Pro	perties		TSE3051	TSE3051-FR	TSE3051-L
Flow	ability		Flowable	Flowable	Flowable
Feat	ures and Benefits		Low viscosity	Low viscosity, UL certified	Low viscosity, low penetration
Visco	osity (23°C)	Pa.s (P)	0.7 (7) 1	0.7 (7) 1	0.7 (7) 1
Cure	Condition	°C/h	125/2	150/1	125/2
Spec	cific Gravity (23°C)		0.97	0.97	0.97
Pene	etration		85	85	65
Ther	mal Conductivity	W/m.K	0.17	0.17	0.17
Volur	me Resistivity	MΩ·m	1.0x10 ⁷	5.0x10 ⁷	1.0x107
Diele	ectric Strength	kV/mm	18	18	18
Diele	ctric Constant (60Hz)		2.8	2.8	2.8
Dissip	pation Factor (60Hz)		0.001	0.001	0.001
Flam	e Retardancy			UL94 V-1	
CC	White				
Color	Transparent				
P	¬ 1kg can		See below matrix	•	•
Pkg	15kg can			•	•

¹JIS K 6249 Typical property data values should not be used as specifications

TSE3051	W	С
1kg bottle		
4kg can		
15kg can		0
20kg pail		0

W: White, C: Clear



Product Details - 2 Part Gels

Properties		TSE	3062	TSE	3070	RTV61	36-D1
Components		TSE3062(A)	TSE3062(B)	TSE3070(A)	TSE3070(B)	RTV6136(A)	RTV6136(B)
Flowability		Flow	able	Flow	able	Flow	<i>r</i> able
Features and Benefits		Low tempe	erature cure	High elon	gation gel	Fast cure, l	ow viscosity
Mixing Ratio ((A):(B) by we	eight)	100	:100	100	:100	100	:100
Color (mixed)		Transp	oarent	Transp	oarent	Trans	oarent
Viscosity (mixed) (23°C)	Pa.s (P)	1.0	(10)1	0.8	(8) ¹	0.75	$(7.5)^2$
Pot Life (23°C)	h	-	1	4	4	0	.5
Cure Condition	°C/h	70/	0.5	70/	0.5	100	/0.3
Specific Gravity (23°C)		0.9	97	0.9	97	0.	98
Penetration		5	5	6	5	6	0
Thermal Conductivity	W/m.K	0.	17	0.	17	0.	19
Volume Resistivity	MΩ·m	1.0>	<10 ⁷	1.0	<10 ⁷	1.0	x10 ⁷
Dielectric Strength	kV/mm	1	8	1	8	20).5
Dielectric Constant (60Hz)		2.	.7	2	.7	2.8 (1kHz)
Dissipation Factor (60Hz)		0.0	001	0.0	001	0.001	(1kHz)
Can		•	•	•	•		
Pail				•	•	(

¹JIS K 6249 ²ASTM D2196 Typical property data values should not be used as specifications

Product Details - 1 Part JCR Grades

Properties		TSJ3187	TSJ3155	TSJ3195-W	TSJ3185
Flowability		Semi-Flowable	Semi-Flowable	Semi-Flowable	Semi-Flowable
Features and Benefits		Thixotropic JCR gel. Provides stress and vibration relief performance	Thixotropic JCR rubber. Low post-cure hardness contributes to stress relief of critical components	Low viscosity JCR gel. Provides stress and vibration relief performance	Thixotropic JCR gel. Provides stress and vibration relief performance
Property		Gel	Rubber	Gel	Gel
Viscosity (23°C)	Pa.s (P)	12 (120) ¹	6 (60) ¹	4 (40) ¹	3 (30)1
Color		Translucent	White	White	Translucent
Cure Condition	°C/h	150/4	150/4	150/4	150/4
Specific Gravity (23°C)		1.00	1.02	1.00	1.01
Hardness		-	11	-	-
Penetration		40	-	80	80
Thermal Conductivity	W/m·K	0.18	0.18	0.18	0.18
Volume Resistivity	MΩ·m	5.0x10 ⁷	1.0x10 ⁷	1.0x10 ⁷	1.0x10 ⁷
Dielectric Strength	kV/mm	25	20	15	15
Dielectric Constant (60Hz)		2.7	2.8	2.8	2.7
Dissipation Factor (60Hz)		0.0006	0.0004	0.0004	0.001
Na ⁺ K ⁺	ppm	<2	<2	<2	<2
Pkg: 500g bottle		•	•	•	•

¹JIS K 6249 Typical property data values should not be used as specifications

Product Details - 2 Part JCR Grades

Properties		XE14-	B5778	TSJ:	3175
Components		XE14-B5778(A)	XE14-B5778(B)	TSJ3175(A)	TSJ3175(B)
Flowability		Semi-F	lowable	Semi-F	lowable
Features and Benefits			ntrollable rubber.	Soft gel contribute	c JCR gel. property s to stress ation relief
Property		Ruk	ober	G	iel
Mixing Ratio ((A):(B) by we	ight)	100	:100	100	:100
Color (mixed)		Trans	lucent	Bla	ack
Viscosity (mixed) (23°C)	Pa.s (P)	14 (140)1	17 (170)1
Pot Life (23°C)	h	8	3	1	2
Cure Condition	°C/h	80)/2	12	5/2
Specific Gravity (23°C)		1.	02	1.	01
Hardness		1	6		-
Penetration			-	7	0
Thermal Conductivity	W/m.K	0.	17	0.	18
Volume Resistivity	MΩ·m	2.0	x10 ⁵	1.0	x10 ⁷
Dielectric Strength	kV/mm	2	24	1	5
Dielectric Constant (60Hz)		2	.7	2	.7
Dissipation Factor (60Hz)		0.0	001	0.0	001
Na+K+	ppm	<	:2	<	:2
Pkg: 500g bottle		•	•	•	•

 $^{^{1}\!\}text{JIS}$ K 6249 $\,$ Typical property data values should not be used as specifications

Product Details - Grease

Properties	TSK5303	TSK5370	TSK550	TSK551	YG6111	YG6240	YG6260	TIG1000
Features and Benefits	Thermally conductive compound for medium heat dissipation. Heat resistance	Compound for electrical insulation & sealing with swell resistant performance	contact insulation protection against		compound for medium heat dissipation. Low	Thermally conductive compound for medium heat dissipation. Low oil separation	compound for medium	compound for medium
Color	White	White	White	Green	White	White	White	White
Specific Gravity	2.34	-	1.03	1.03	2.45	2.45	2.30	2.50
Penetration	330	270	220	220	310	290	300	340
Bleed (150°C, 24h) %	2.8	1.5	1.5	1.0	0.4	0.0	0.5	0.1
Evaporation (150°C, 24h) %	0.2	0.2	0.2	0.3	0.1	0.4	0.1	0.1
Thermal Conductivity W/m.K	0.84	-	-	-	0.84	0.84	0.84	1.00
Volume Resistivity MΩ·m	-	1.0x10 ⁵	2.0x10 ⁷	2.0x10 ⁷	2.0x10 ⁶	2.0x10 ⁶	2.0x10 ⁷	3.0x10 ⁶
Dielectric Constant (60Hz)	5.0	2.5	2.8	2.8	5.0	5.0	5.0	5.0
Dissipation Factor (60Hz)	0.005	0.0001	0.0002	0.0002	0.006	0.006	0.005	0.006
Low Molecular Siloxane (D4-D10) wt%	0.0015	0.01	-	-	0.01	0.003	0.003	0.003
Arc Resistance ¹ s	-	-	120<	120<	-	-	-	-
Low Volatility	•	•			•	•	•	•
Temperature Resistance	•							
Thermally Conductive	•				•	•	•	•
Low Bleed						•		
Tube		•	•	•	•	•	•	
Packaging Pail	•		•	•	•	•	•	•
ng Pail			•			•	•	

Typical property data values should not be used as specifications

	Overde	Oalar	Thickness	R	TI	Flame	HWI	HAI	HVTR	D495	СТІ	File
ype	Grade	Color	mm	Elec.	Mech.	Class	(PLC)	(PLC)	(PLC)	(PLC)	(PLC)	No.
	ECS0601	Black Clear White	1.5	105	105	НВ	-	-				E5674
	FOOODOOFD	Gray	0.2	105	105	V-0	-	-				EE074
	ECS0609FR	Gray	3.0	105	105	V-0	-	-				E5674
		Gray	1.0	105	105	V-1	0	0	0	1	0	
	TN3085	Gray	3.0	105	105	V-0	0	0	0	4	0	E5674
	INSUOS	White	1.0	105	105	V-1	2	0	0	3	0	E3074
		White	3.0	105	105	V-0	1	0	U	J	U	
		Black	0.71	105	105	V-1	3	0				
	RTV133	Black	1.6	105	105	V-1	2	0	0	3	0	E3695
		Black	3.4	105	105	V-0	1	0				
		White	0.75	105	105	HB	4	0				
	RTV160	White	1.5	105	105	HB	3	0	1	5	0	E3695
	NIVIOU	White	2.5	105	105	HB	3	0	'	J	U	L3090
		White	3.0	105	105	HB	-	-				
		Gray	0.83	105	105	HB	3	0				
	RTV167	Gray	1.5	105	105	НВ	2	0	0	5	0	E3695
		Gray	2.6	105	105	НВ	2	0				
		Clear White	0.75	105	105	НВ	4	0				
	TSE382	Clear White	1.5	105	105	НВ	3	0	0	1	0	E5674
	13E302	Clear White	1.9	150	140	НВ	3	0	U	4	0	E3072
1 Par		Clear White	3.0	150	140	НВ	3	0				
Part Condenstaion Cure	TSE3826	Red	2.0	200	200	-	-	-				E5674
Conc	13E3020	Red	3.0	200	200	-	-	-				E3072
lens:		White	1.1	105	105	V-1	-	-				
taior		White	1.5	105	105	V-1	0	0				
Cu	TSE3843-W	White	1.9	150	140	V-1	-	-	0	1	1	E5674
6		White	2.5	150	140	V-1	-	-				
		White	3.0	150	140	V-1	-	-				
		Black	1.2	105	105	V-0	0	0				
	TSE384-B	Black	1.9	150	140	V-0	-	-	0	3	1	E5674
		Black	3.0	150	140	V-0	-	-				
	TSE3853-W	White	1.5	105	105	V-0	0	3	0	3	0	E5674
	1020000 VV	White	3.0	105	105	V-0	0	3		U		20072
		Gray	0.75	105	105	V-0	0	0				
		Gray	1.5	105	105	V-0	0	0				
	TSE3854DS	Gray	3.0	105	105	V-0	0	0	0	3	0	E5674
		White	1.5	105	105	V-0	0	3				
		White	3.0	105	105	V-0	0	3				
	TSE389	Clear White Black	1.5	105	105	НВ	-	-				E5674
	102000	Clear White Black	3.0	105	105	НВ	-	-				20072
		Gray	0.75	105	105	V-0	-	-				
	TSE3944	White	0.75	105	105	V-1	-	-	0	3	0	E5674
	100044	Gray White	1.5	105	105	V-0	0	0	U	U	U	20072
		Gray White	3.0	105	105	V-0	0	0				
	TN3305	Clear White Black	1.5	105	105	НВ	-	-				E5674
	1110000	Clear White Black	3.0	105	105	НВ	-	-				L3074

RTI: Relative Temperature Index PLC: Performance Level Category HWI: Hot Wire Ignition HAI: High-Current Arc Ignition HVTR: High-Voltage Arc Tracking Rate D495: D495 High-Voltage Dry Arc Resistance CTI: Comparative Tracking Index

_		2.1	Thickness	R	RTI	Flame	HWI	HAI	HVTR	D495	СТІ	N
Туре	Grade	Color	mm	Elec.	Mech.	Class	(PLC)	(PLC)	(PLC)	(PLC)	(PLC)	File No.
		Black	0.64	105	105	НВ	-	-				
<u> </u>	TSE3976-B	Black	1.5	105	105	НВ	-	-				E56745
So		Black	3.0	105	105	НВ	-	-				
1 P Cond Cure	XE11-A5133S	White	3.0	105	105	V-1	-	-				E56745
enu	VE11 DE000	White	1.5	105	105	НВ	-	-				EE674E
	XE11-B5320	White	3.0	105	105	НВ	-	-				E56745
	TSE3051-FR	Clear	2.7-3.3	105	105	V-1	-	-				E56745
		NC	1.0	105	105	НВ	-	-				
art H	TSE322S N	NC	1.5	105	105	НВ	-	-				E56745
1 Part Heat Cure		NC	3.0	105	105	НВ	-	-				
Cure	TOFOOE	Red	1.0	105	105	НВ	-	-				EE674E
	TSE326	Red	3.0	105	105	НВ	-	-				E56745
		Black	1.0	105	105	V-0	-	-				
	T0F0001	Black	1.6	105	105	V-0	2	0	0	0	0	F50745
	TSE3331	Black	2.0	105	105	V-0	-	-	0	0	0	E56745
		Black	3.0	105	105	V-0	0	0				
	TOFOOOTIV	Black	2.5	105	105	V-0	-	-				E56745
	TSE3331K	Black	3.0	105	105	V-0	-	-				E30743
	TOFOOOTIV FV	Black	2.5	105	105	V-0	-	-				EE674E
	TSE3331K EX	Black	3.0	105	105	V-0	-	-				E56745
	TSE3431	Gray	2.0	105	105	V-1	-	-				E56745
	1353431	Gray	4.0	105	105	V-0	-	-				E30743
2 Part		Gray	1.0	105	105	V-0	0	0				
art	TSE3431-H	Gray	1.5	105	105	V-0	-	-	0	4	4	E56745
	1353431-11	Gray	2.5	105	105	V-0	0	0	0	1	ı	E30743
		Gray	3.0	105	105	V-0	-	-				
		Gray	1.0	105	105	V-1	-	-				
	TSE3664K	Gray	2.0	105	105	V-0	-	-			1 E5674	E56745
		Gray	3.0	105	105	V-0	0	0				
	XE14-B7892	Black	2.0	105	105	V-1	-	-				E56745
	VF14-D1095	Black	3.0	105	105	V-0	-	-				LJ0745
	TSE3661	All	1.0	105	105	НВ	4	0			0	E56745
	1323001	All	3.0	105	105	НВ	3	0				L30743
	TIA222G	Gray	3.0 - 3.3	105	105	V-0	-	0	0	2	0	E56745

HWI	HAI	HVTR	D495	CTI
when exposed to high temperatures. Expressed as the mean number of seconds required to lightly a specimen $\frac{1}{2}$	Ability to withstand electrical arcing. Expressed as the number of arc rupture exposures required to lighte a specimen when the arc occurs directly on the surface or a specified distance above the test specimen.	Expressed as the rate (inches per minute) that (a tracking path can be produced on the surface of the material under standardized test conditions. Expressed as the rate HVTR Range (in mm/min) PLC 10 10 10 10 10 10 10 10 10 10 10 10 10	number of seconds that a material resists the formation of a surface- conducting path 200 350 250	Expressed as that Tracking Index voltage which causes tracking after 50 drops of 0.1% ammonium chloride solution have fallen on the material. Expressed as that Tracking Index (volts) PLC 2000 PLC (volts) PLC 2000 PLC (volts) PLC 2000 PLC (volts) PLC 2000

Typical Adhesion Performance

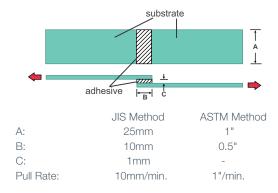
Condensation Cure Grades

			Alk	оху			Acetoxy			Oxi	me	
	Substrate	Primer- less	ME121	ME123	XP80-A5363	Primer- less	ME121	ME123	Primer- less	ME121	ME123	XP80-A5363
	Copper	•	•			● ¹	● ¹		▲ ¹	●1		
	Steel	•	•			A	•		•	•		
7	Brass	•	•			▲ ¹	▲ ¹		▲ ¹	●1		
Metals	Stainless Steel	•	•			A	•		•	•		
S	Aluminum	•	•			•	•		•	•		
	Galvanized Steel	•	•				•		•	•		
	Tin	•	•			•	•		•	•		
	Acrylic Resin	•		•		×		•	•	•		
	Phenol Resin	•		•		•		•	•	•		
	Epoxy Resin	•		•		•		•	•	•		
	Polycarbonate	•		•					•	•		
	Soft Polyvinyl Chloride	•		•		×		•	×	×	•	
	Rigid Polyvinyl Chloride	•		•		•		•	•	•	•	
	Polyester Film	•		•		A		•	•	•	•	
П	Unsaturated Polyester	•		•		•		•	•	•	•	
Plastic	Polyamide	•		•		•		•	•	•	•	
<u>C</u>	Nylon 66	•		•					•		•	•
	PBT	•		•					A		•	
	PPS	•		•					A		•	•
	ABS	•		•		•		•	•	•	•	
	Polypropylene	×		×	•				×	×	×	•
	Polyethylene	×		×	A	×		×	×	×	×	
	Fluorocarbon Resin	×		×		×		×	×	×	×	
	Silicone Resin Laminate	•		•		•		•	•	•		
	Chloroprene Rubber	A		•		A		•	A		•	
D	Nitrile Rubber	A		•		•		•	A		•	
Rubber	Styrene Butadiene Rubber	A		•					A		•	
er	Ethylene Propylene Rubber	A		•					A		•	
	Silicone	•		•		•		•	•		•	
Inorg	Glass	•	•			•	•		•	•		
Inorganic	Ceramic	•	•			•	•		•	•		

Adheres completely, ▲ Adheres, but separates from surface when pulled, x Does not adhere
 May corrode under some usage conditions

			Condensa	ation Cure			A	Addition Cure					
Primer Properties	ME121	ME123	XP80-A5363	SS4004P	SS4044P	SS4179	ME151	XP81-B0016	SS4120				
Appearance	Yellow Transparent	Yellow Transparent	Yellow Transparent	Pink	Yellow	Clear Colorless	Yellow	Yellow Transparent	Clear Colorless				
Substrates	Metals, Glass, Plastic	Plastic, Rubber	Polylefins	Metals	Metals	Plastic	Metals, Glass, Plastic, Ceramic	Metals, Glass	-				
Specific Gravity (23°C)	0.85	0.86	0.88	0.85	0.85	0.98	0.87	0.71	0.82				
Non-Volatile Content	15%	15%	7%	15%	15%	6%	24%	7.5%	3%				
Drying Time (23°C) min	30	30	20	30	30	15	30	30	30				
Solvents	Acetone Toluene IPA	Acetone Toluene IPA	Toluene	Acetone Xylene N-butanol IPA	Acetone Xylene N-butanol IPA	Ethyl Acetate Toluene Methanol	Toluene IPA	n-hexane	Ethanol Methanol				

Shear Adhesion Test Method



Typical Chemical Resistance

Chemical		Volume Change				
Acid	Concentrated Hydrochloric Acid	©				
	Hydrochloric Acid (3%)	0				
	Concentrated Sulphuric Acid	Decomposition				
	Sulphuric Acid (10%)	0				
	Concentrated Nitric Acid	Δ				
	Nitric Acid (7%)	0				
	Glacial Acetic Acid	0				
	Acetic Acid	0				
	Hydrofluoric Acid	Decomposition				
	Citric Acid	0				
	Phosphoric Acid	0				
ali	Concentrated Ammonia	0				
	Ammonia (10%)	0				
	Potassium Hydroxide (20%)	0				
Alkali	Sodium Hydroxide (1%)	0				
	Sodium Hydroxide (20%)	0				
	Sodium Hydroxide (50%)	0				
line	Sodium Chloride (10%)	0				
c Sa ution	Sodium Carbonate (2%)	0				
Inorganic Saline Solution	Sodium Carbonate (20%)	0				
Inor	Hydrogen Peroxide (3%)	0				
	ASTM No.1 Oil (150°C, 70h)	0				
	ASTM No.3 Oil (150°C, 70h)	Δ				
IIO	Mineral Oil	0				
	Castor Oil	0				
	Flax Seed Oil	0				
	Silicone Oil (35°C, 70h)	Δ				
	Acetone	Δ				
	Butyl Alcohol	0				
Solvent	Ethyl Alcohol	0				
	Gasoline	X				
	Mineral Spirit	X				
	Toluene	X				
er	Water (room temperature)	©				
Water	Boiling Water (70h)	0				
	© <10% ○ 10-25% △ 25-75% X × 75%					

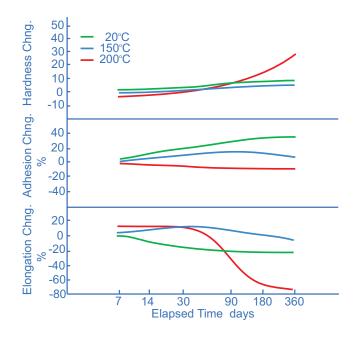
 \bigcirc : <10%, \bigcirc : 10-25%, \triangle : 25-75%, X: >75%

Test Method:

Volume change of cured silicone rubber after immersing 1 week at 25°C

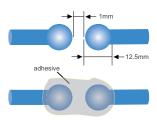
Typical Heat Resistance

1-Part Condensation Cure Adhesive (Alkoxy Type)



Typical Electrical Performance

Dielectric Strength Test Method: Equipment: Dielectric voltage gauge Voltage Rise: 1kV/s Terminal Gap: 1mm (JIS C 2110)



Electrical Performance of Cured Material

TSE3843-W	Volume Resistivity MΩ·m		Dielectric Strength kV/mm	
Conditions	40°C, 95%RH	25°C Immersed	40°C, 95%RH	25°C Immersed
Initial	1.6x10 ⁷	1.6x10 ⁷	29	29
1 Day	2.9x10 ⁶	2.2x10 ⁶	27	25
3 Days	2.5x10 ⁶	3.6x10 ⁶	29	22
7 Days	2.7x10 ⁶	1.9x10 ⁶	24	23

Other Electronic Solutions from Momentive Performance Materials



Provides detailed information on silicone materials used for thermal management applications in electronics and micro-electronics. Includes SilCool* grease & adhesives, and conventional grades for adhesion, encapsulation and potting.



Provides opto-electronic solutions for LED Packages and Assemblies. Includes InvisiSil* LED encapsulants, Glob Top, Lens fabrication materials, Die Attach adhesives, and Dot Matrix assembly materials.

Frequently Asked Questions

What does RTV mean?

RTV stands for Room Temperature Vulcanization (cure). Despite the low-temperature connotations conveyed by this name, RTV silicones consist of both Room Temperture Cure and Heat Cure grades.

What is the cure mechanism of a condensation cure product?

Condensation cure silicone products cure when exposed to atmospheric moisture. Moisture in the air is generally required to cure (or vulcanize) condensation cure products. The cure process begins from the outer surface, and therefore time is required for complete cure. The cure time is affected by the reaction mechanism and viscosity of the material. Generally, at 25C and 50%RH, condensation cure RTV silicones cure through in 24 to 48 hours. Full physical properties may take up to 7 days to develop.

What is the depth (bead thickness) limit for a condensation cure grade?

For 1-part, condensation cure products, the depth (bead thickness) limitation is approximately 6mm (1/4"). For 2-part, condensation cure products, the depth (bead thickness) limitation is approximately 25mm (1").

Can I accelerate the cure time of a 1-part product?

Condensation cure silicone cure rates depend on humidity, silicone thickness, and to a smaller degree heat. Increasing the relative humidity around the silicone or reducing the thickness of the material will reduce the time to cure the material. Increased heat (not over 50C) will somewhat reduce cure time but as mentioned will do so to a much smaller degree than humidity or thickness.

What is the cure mechanism of an addition cure product?

Addition cure silicone RTV products may be 1 or 2-part and cure when exposed to heat.

Although some heat cure products can cure at room temperature, higher heat greatly accelerates the cure. 1-part heat cure products typically have an inhibitor in the formulation that stops the product from curing until an activation temperature, greater than room temperature, is achieved and the inhibitor is driven off and the cure reaction is allowed to proceed.

What does "tack free time" mean?

Tack free refers to the amount of time it takes for a condensation cure silicone product to form a cured outer layer (the cured outer layer is not tacky like uncured material).

What is "mix ratio"?

Mix ratio is a term used to state the amount of each material to be in a multi-component material. The mix ratios for 2-part products are described on the individual product data sheets and are given as a ratio by weight of each material.

What does "pot life" or "work life" mean?

The amount of time after a 2-part grade is mixed with its curing agent that it will remain useful or pliable.

How do I remove silicone?

Before it is cured: use a putty knife to remove any of the uncured paste. Wipe the area clean with isopropyl alcohol to remove any leftover residue. After it is cured: First mechanically remove as much of the silicone as you can with either a knife or a razor. A solvent (mineral spirits, toluene, xylene, acetone) can them be used to remove any oily residue or any remaining silicone, It may be necessary to soak the silicone in a solvent overnight to break it down.

Can I thin a silicone?

Silicone can be thinned using a solvent in which the silicone is miscible, generally an aromatic solvent such as toluene or xylene. As always, be sure to follow the producer's instructions when using solvent products and always use in a well-ventilated area. The shrinkage of the silicone and the cure time will increase with the addition of solvent. Alternative suggestions would include non-

reactive fluids or an RTV with a lower viscosity.

What can I do to improve the adhesion of the silicone adhesive to my parts?

The first step to good adhesion is to have clean surfaces for the silicone to bond to. For difficult-to-bond-substrates, Momentive Performance Materials offers a number of primers that can be used to improve and maximize adhesion.

How do I ensure that air is removed from 2-part grades?

If you are hand mixing, air may become added to the material during the mixing process. Vacuum de-airing is most effective in removing air prior to use. Automated mixing equipment that utilizes a static mixer can eliminate the need to de-air prior to dispensing.

On complex high-density electronics, air can sometimes be trapped under components during the potting process. Where this is a concern, potting under vacuum or vacuum de-airing after potting can remove the trapped air. An alternate approach may be to use a grade with a low viscosity and longer potlife and to cure at lower temperatures (if heat-cure grade), allowing entrapped air to escape prior to the cure of the material.

What is cure inhibition, and how do I prevent it?

Cure inhibition is a phenomenon that may be observed in addition-cure grades. These materials use a platinum catalyst to drive the curing reaction. Surfaces containing water, sulphur, nitrogen compounds, organic metal compounds, or phosphate compounds, may inhibit cure.

Cure inhibition is characterized by a gummy or sticky appearance of the silicone at the interface between the silicone and offending substrate. Inhibition can be prevented by application of a barrier coat, cleaning of the offending material prior to application of the silicone material, replacing the offending material with a suitable alternative, or selection of a condensation cure grade.

Dispensing Equipment Examples



Tube Type Dispensing Unit



Cartridge Air-Gun Dispensing Unit



Small Can Pump and Dispensing Unit



Cartridge Type Dispensing Unit



Pail Can Pump Unit

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